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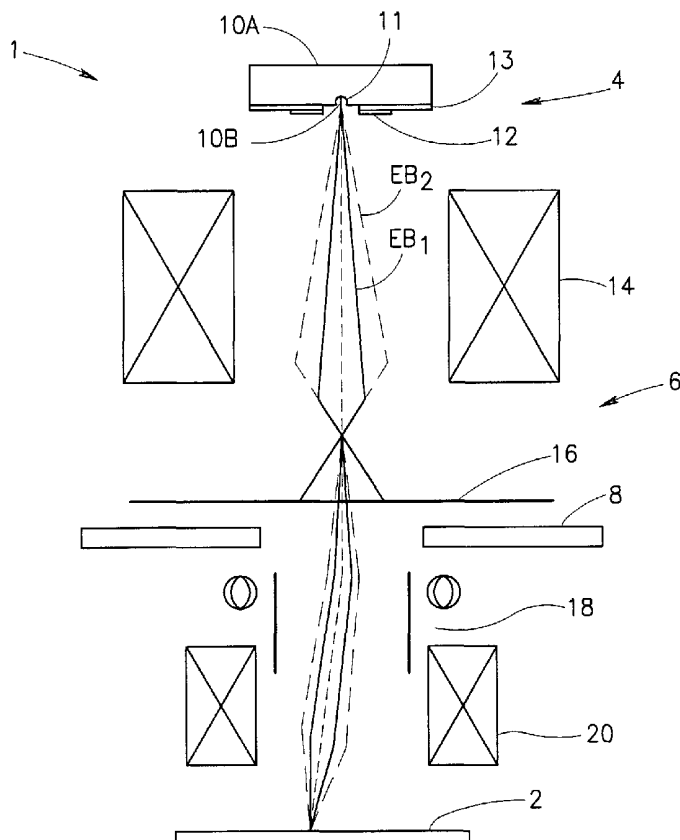
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(54) Title: A NANOTUBE-BASED ELECTRON EMISSION DEVICE AND SYSTEMS USING THE SAME



(57) Abstract: A device that produces an electron beam with high optical quality for processing a sample, is presented. The optical quality is manifested by very high brightness and low energy spread. The device includes an electron source device comprising an electrode in the form of a shaped first layer, preferably in the form of a conducting crater carrying at least one nanotube, and an extracting electrode, which is formed with at least one aperture and is insulated from the first layer. The source can be used in any column that requires such properties. The column according to the invention may be a full size or a miniature electron microscope, a lithography tool, a tool used for direct writing of wafers or a field emission display.



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A Nanotube-Based Electron Emission Device and Systems Using the Same

FIELD OF THE INVENTION

This invention is generally in the field of electron emission based techniques, such as electron microscopy (EM), specifically scanning electron microscopy (SEM), and electron beam lithography (EBL), utilizing a nanotube-based electron emission device, with high electron optical quality, specifically high
5 brightness and low energy spread. The electron emission device of the present invention can be used with any electron beam column or other system that requires such properties.

BACKGROUND OF THE INVENTION

10 It is the common goal of various applications utilizing an electron beam source, such as SEM and EBL, to have a simple and stable electron beam source, in particular, a source capable of being installed in a miniature device and having high electron optical quality. The simplicity of the electron source is defined by its working conditions, such as operating vacuum and temperature parameters. As for
15 the optical quality, it is predominantly determined by the brightness (i.e., current density per solid angle) and the energy spread of the electron beam. Both the brightness and energy spread determine the amount of current that can be focused on a small spot on the surface of a sample.

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SEM and EBL are known techniques widely used in various applications, such as the manufacture of semiconductor devices. Electron sources conventionally used in SEM and EBL tools are typically one of three kinds: thermal sources, cold field emitters (CFE), and thermal field emitters or “Schottky-emitters”.

5 An electron beam generated by a thermal source has a wide energy spread, i.e., about 2eV for tungsten filaments and 1.2eV for LaB₆, and low brightness, i.e., about 10⁵-10⁶A/cm²sr. Consequently, the electron sources of this kind require the complicated construction of an electron beam column, as well as high acceleration voltage, to achieve the resolution of a 1-10nm.

10 CFE are characterized by a higher brightness (about 10⁸-10⁹A/cm²sr) and a narrower energy spread (about 0.3-0.4eV), as compared to that of thermal sources. It is usually made of single crystal tungsten. Such a cathode-electrode requires “flashing” at a high temperature (more than 1800K) to clean and reform its surface. Moreover, CFE suffer from ultra-high vacuum requirements (e.g., 10⁻⁹-10⁻¹⁰ Torr),
15 which is a major factor in the cost of a CFE-based device. Due to the unavoidable adsorption of molecules on the tip-like cathode-electrode, it is complicated to operate CFE in a stable manner.

A TFE source utilizes a compromise concept between those underlying the implementation of the electron sources of the above two kinds. TFE are made of
20 tungsten coated by zirconium oxide, aimed at lowering the work function. These sources, as compared to CFE, are more stable, require lower vacuum (about 10⁻⁸-10⁻⁹ Torr), and have a comparable high brightness (about 10⁷-10⁸A/cm²sr). A TFE source still requires an ultra high vacuum. A further drawback is associated with the need to stabilize the system at a high working temperature, i.e., about
25 1800°C. The voltage required to achieve a desirable high resolution is typically high. This may damage the sample and/or cause undesirable charging thereof. To solve this problem, beam deceleration may be employed. However, this complicates the construction of an electron beam column, and enhances chromatic aberrations. All the conventional electron sources use a very small fraction of the
30 current that is emitted from the electron source. A state of the art Schottky source

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emits about $100\mu\text{A}/\text{sr}$ with only 10nA of the source current in a TFE gun can actually be used as a probe current.

As a result of the above disadvantages of the conventional electron sources, their use in EM and EBL tools make these tools expensive and bulky. This impedes
5 their application as integrated tools. Indeed, when using SEM for the inspection of workpieces on a production line, for example, in the manufacture of semiconductor devices, SEM is typically a stand-alone machine accommodated outside the production line. Accordingly, workpieces to be inspected are removed from the production line and brought to the SEM. This slows the production. Moreover, any
10 unnecessary handling of such delicate workpieces as semiconductor wafers is undesirable. Thus, it is highly desirable to use a miniaturized SEM that can be brought to the sample to be inspected, rather than bringing the sample to the SEM. The miniaturized SEM technology is known as “micro-columns”. As for the lithography tools, it is a core challenge of the semiconductor industry, to go beyond
15 optical resolution, which currently limits the minimal feature size of the active elements of a semiconductor device.

Electron beam lithography is not limited by the optical diffraction limit, but by the throughput of the electron beam apparatus. There are three main approaches to this problem. First, the use of a miniature electron beam source device that can
20 be utilized in an arrayed operation (“micro-columns”); second, direct writing in “proximity focus”; and third, the SCALPEL (Scattering with Angular Limitation Projection Electron Beam Lithography). Although these technologies have been known for several years, none of them is used in commercial applications. This is due to the following reasons: The miniaturized arrayed operation is limited by the
25 absence of an adequate electron source, which has the desired electron optical quality (high brightness and low energy spread), which is compatible with miniaturization and with silicon technologies, and which can be produced with sufficient alignment to the optical axis. Currently micro-columns utilize a TFE. The high temperature of the TFE sources places additional limitation on the
30 micro-columns. The proximity focus electron-beam writing was not utilized due to

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the absence of an electron source that can be patterned in the sub-100nm scale and that emits electrons with the required electron-optical quality, specifically, a sufficiently narrow angular distribution. The SCALPEL technology is limited by several factors, notably, the small area that can be uniformly exposed by the
5 currently available electron sources.

Attempts have been made to develop electron beam sources with improved electron-optical quality and operating vacuum parameters, so far with no success. Concurrently, carbon-based nanotubes have been developed and studied as field emitters. Their main properties and advantageous features are disclosed, for
10 example, in the following publications:

- Shoushan Fan et al., "*Self-Oriented Regular Arrays of Carbon Nanotubes and Their Field Emission Properties*", Science, Vol. 283, p. 512-514, January 1999;

- O.H. Wang et al., "*Field Emission from nanotube Bundle Emitters at Low
15 Fields*", Appl. Phys., Lett., 70 (24), pp. 3308-3309, June 1997;

- J.M. Bonard et al. "*Field Emission Induced Luminescence from Carbon Nanotubes*" Phys. Rev. Lett., 81, 1441, 1998;

- Phillip G. Collins and A. Zettl "*A Simple and Robust Electron Beam Source from Carbon Nanotubes*", Appl. Phys. Lett., 69 (13), pp. 1969-1971,
20 September 1996;

- Walt A. de Heer et al., "*A Carbon Nanotube Field Emission Electron Source*", Science, Vol. 270, November 1995;

- O.G. Wang et al. "*A Nanotube-Based Field-Emission Flat Panel Display*", Appl. Phys. Lett., Vol. 72, No. 22pp. 2912-2913, 1998;

25 - WO 98/11588; WO 96/42101; EP 0913508; US 5,973,444; WO 98/05920; and US 5,872,422;

Various molecular morphologies can be grown, known as MWNT (Multi Wall Nano Tubes) and SWNT (Single Wall Nano Tubes). MWNT may be produced as capped or open, and SWNT can appear also as tight bundles. The various
30 nanotubes have been grown with diameters down to a few nanometers.

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Although nanotubes are known to have exceptionally good field emission properties (high current at low applied voltage, as well as low energy spread) they did not find their application in EM or EBL. This is largely because the brightness of "bare" carbon nanotubes is essentially low as compared to that of a TFE source.

5 Thus, it is essential to design a gun with superior optical properties that will utilize the elevated field-emission properties of the nanotubes.

According to a technique disclosed in the article of Saito et. al., Nature, vol. 389, 9th Oct 1997, pp 554-5, carbon nanotubes were suspended against an anode plate to obtain a light spot on a fluorescent screen. The source's virtual angular

10 divergence observed was of the same order of magnitude as that of a conventional TFE source, but the total emitted current is lower. This is a strong indication that simply replacing a conventional electron source with a nanotubes-based source does not constitute a satisfactory improvement of the brightness of the source.

As indicated above, the requirement for a miniature electron source is more

15 essential with the development of the micro-column. Prior art techniques of the kind specified disclosed, for example in the articles of Kratchmer et al, JVS, **B13**, 2498 (1995) and Yu et al, JVS **B13**, 2436 (1995), and in US Patent No. 6,023,060, use a "point" electron source which, in principle, emits a diverging laminar electron beam, which is then "cropped" at an aperture (or through a few apertures). These

20 techniques utilized either a CFE or a miniaturized Schottky TFE.

Several publications disclose the emission properties of a single nanotube. The current, I , vs. voltage, V , properties of a single nanotube has been disclosed by Saito et al, App. Surf. Sci. **146**,305(1999), Dean et al, J. Appl. Phys. **85**, 3832(1999) and Rinzler et al Science, **269**,1550(1995). In all these experiments, a

25 few nanometers thick nanotube (of various morphology) was attached to a thin conductor and suspended vertically against an anode plate. In these experiments the distance between the anode and the cathode-tip ranged from about one millimeter to a few centimeters.

In order to compare between the experiments one needs to compare the

30 current vs. the electric field on the tip, the latter being determined by the applied

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voltage and the experimental setup. If one assumes that the reference electric field is the fixed electric field between two parallel plates separated by a distance, d , which is equal to the distance between the end of a tip and a flat anode plate, then one finds by simple calculation that the electric field on the tip of a very long (to be
5 considered infinite or suspended) and a few nanometers diameter nanotube is enhanced relative to V/d by about two orders of magnitude. In all the above experiments, V/d vs. I may be compared, while taking the field enhancement and the material work function as having the same order of magnitude. One finds that in all the above independent experiments, the current appears at a threshold value
10 of V/d and that the best performing types of nanotubes produce approximately 500nA at $V/d \approx 0.05 V/\mu m$. In all cases, a saturation current is obtained. From the results of Saito et al, Nature **389**, 554(1997), the angular divergence of the electron beam can also be estimated, as a spot of about 1cm diameter is seen on a fluorescent screen at a distance of 6cm. This gives an angular current density of
15 about 40 μ A/sr for a maximum current of 900nA.

Thus, a single nanotube device can produce a relatively large current for a very low extracting voltage at a distance between a nanotube-tip and anode plate of the order of 1 μ m, but the angular current density will be too small to simply replace the TFE gun utilized within the known designs of micro-columns.

20 US Patents 5,773,921 and 5,973,444 and EP0913508 disclose various techniques of micro-fabricating a single nanotube and a plurality of nanotubes on a conducting substrate. In all of these field emission (FE) devices consisting of one or more nanotubes attached to a conducting substrate and separated by an insulating layer, a low voltage extracting gate is utilized. These designs are to be considered
25 "bare", as they simply provide a beam governed by the initial angular divergence. From the angular current density calculated above, it is clear that this device is insufficiently bright as an electron gun for a SEM, EBL or micro-column. As a specific example, if one applies the scaling rules developed by Chang et. al., JVS **B7**, 1855(1989), to a single nanotube device of this type, it is clear that this device

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is not appropriate as an electron source in a dual immersion lens electron gun device.

5

SUMMARY OF THE INVENTION

There is accordingly a need in the art to improve electron source based devices, designed to provide a high brightness and low energy spread, utilizing one or more nanotubes as field emitters.

10 It is a major feature of the present invention to provide such an electron emission device, which is sufficiently miniature and provides a beam with very high electron optical quality, as required for electron microscopy and other applications. In particular, to improve the brightness of the source the initial angular divergence of the electron beam is to be decreased, as compared to that
15 obtained with the devices of the kind specified disclosed in the above prior art publications.

Generally, the design concept proposed in this invention for reducing the angular divergence of the beam can be applied to other miniature electron sources or macroscopic point sources, and is not limited to nanotubes.

20 It is a further feature of the present invention to provide such a device, which enables various, important, novel applications of the electron beam source.

A central idea of the present invention is based on the implementation of an electron source with a cathode-electrode which is formed by one or more nanotubes within a specially designed environment, and is associated with one or more gates
25 formed by an anode electrode. According to the technique of the present invention, this is done in a way that minimizes the angular divergence of the beam to the extent that the invention discloses a gun that produces a nearly laminar electron beam. This electron source allows a significant fraction of the current that is emitted from the gun, to be used in a probe. Such an electron source may be used in

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an electron microscope, either for scanning or transmission purposes, in a lithography tool, in a field emission display and for direct writing purposes.

The nanotube-based electron gun is expected to require lower vacuum conditions (about 10^{-6} - 10^{-7} Torr), as compared to that required by conventional
5 electron sources. The relaxed vacuum requirement is due to the fact that nanotubes are less sensitive to adsorption than conventional emitters. Another reason for the lower vacuum requirement is the “point on a plane” configuration: the nanotubes are situated on a conducting surface, the lines of the electric field are effectively directed between the two planes. Thus, the tendency of ions to be accelerated
10 towards the emitter is significantly decreased.

According to the gun design proposed in the invention, the nanotubes can be assembled in a way that provides very high brightness. The high brightness, combined with the low energy spread (about 0.1eV), enables a resolution of less than 1nm to be provided with relatively low accelerating voltages. Since the
15 brightness of the beam, as it exits the electron gun, is high, an optical column attached to the gun can be significantly shorter than the micro-columns known so far. Since heating of the tip-electrode to high temperatures is not required and since the emission drift is small, a carbon nanotube-based bright electron source has obvious advantages.

20 It is important to note that using one of the nanotubes growing techniques disclosed in the literature (e.g. CVD growth, as disclosed in Shoushan Fan et al., Science, Vol. 283, p. 512-514, 1999 for dense nanotubes, or the technique disclosed in Z. F. Ren., App. Phys. Lett., Vol. 75, p. 1086-1088, 1999 for a single nanotube), the manufacture of such an electron source device can be built in a compatible way
25 to the known silicon processes. The nanotubes are grown self-aligned to an extraction electrode. In a micro-column, they can also be aligned with the other column components. The desired dimensions and optical properties of the gun can be readily determined by charged particle dynamics simulation, which take into account space-charge effects (TRICOMP, by Field Precision, Albuquerque, NM,
30 USA).

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Due to the above advantages of the electron source device, its use in a SEM in the manufacture of semiconductor devices will significantly increase the SEM's throughput, due to the shorter pumping time of a sample and due to the fact that the inspection can be done in-situ. It will further increase the throughput due to the ability to provide an arrayed (parallel) operation of a number of columns.

Thus, according to one aspect of the present invention, there is provided a device to be applied to a sample for processing it by an electron beam, the device comprising an electron source device that comprises an electrode in the form of a first conductive layer carrying at least one electrons emitting fiber located inside a crater formed in said first conductive layer for collimating the electron beam produced by the fiber, and an extracting electrode insulated from the first layer, the extracting electrode being formed with at least one aperture located above the crater, the device thereby providing a desired angular divergence of the electron beam.

The term ***“processing”*** used herein signifies any treatment that can be applied to a sample by means of an electron beam, such as monitoring, inspection/review, patterning (including mask-making), excitation (e.g., causing the sample's luminescence), etc. The device can be used for an electron microscope (e.g., SEM), a lithography tool, a field emission display, etc. The term ***“crater”*** signifies a groove made in the first electrically conductive layer, the electrons emitting fiber projecting from the bottom of the groove. The term ***“desired angular divergence of the beam”*** signifies a significantly reduced angular divergence, as compared to that of the prior art devices of the kind specified. The electron-emitting fiber is preferably a nanotube.

The electron source device may be attached to an electron beam column, which can be a miniaturized electron optical system, such as the micro-column. The provision of the electrons emitting fiber inside the electrically conductive crater enables to collimate the emitted beam, thereby significantly increasing the brightness at the exit of the electron source device. Because of the high brightness at the exit of the specified electron gun, the micro-column may be simplified and

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further miniaturized. For example, it is expected that no further collimation will be required after the gun. Therefore, the device may consist of the gun, the scanner, the detector, and possibly fewer lenses.

The first conductive layer may carry a plurality of electrons emitting fibers
5 (e.g., nanotubes), wherein either several fibers are located in the same conductive crater, or an array of such conductive craters is provided, each for carrying a corresponding one of the fibers.

The ability to control the growth pattern of the nanotubes provides a novel application of the electron source device in a lithography tool for producing the
10 desired features of a semiconductor device on the sample (e.g., wafer), in proximity focus. In other words, the nanotubes are grown on catalysts that are shaped in the form of the desired pattern. The conductive regions, where the catalysts are placed, are built as a two-dimensional cross-section of the conducting crater design disclosed in the current invention, namely, with a specific construction to reduce
15 the angular divergence of the beam.

There is thus provided, according to another aspect of the present invention, an electron microscope to be applied to a sample, the microscope comprising an electron source device and an electron beam column, wherein the electron source device comprises an electrode in the form of a first conductive layer carrying at
20 least one electrons emitting fiber located inside a crater formed in said first conductive layer for collimating the electron beam produced by the fiber, and an extracting electrode insulated from the first layer, the extracting electrode being formed with at least one aperture located above the crater, the device thereby providing a desired angular divergence of the electron beam.

25 According to yet another aspect of the present invention, there is provided a lithography tool for processing a sample to form its surface with a predetermined pattern, the tool comprising an electron source device having a plurality of electrons emitting fibers producing a plurality of beams each corresponding to one of the pattern features, the beams being spatially separated and aligned in a manner

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corresponding to the alignment of the pattern features to be obtained on the surface of the sample. The sample itself may serve as an extracting electrode.

More specifically, the present invention utilizes nanotubes as electrons emitting fibers, and is therefore described below with respect to this application.

5 BRIEF DESCRIPTION OF THE DRAWINGS

In order to understand the invention and to see how it may be carried out in practice, a preferred embodiment will now be described, by way of non-limiting example only, with reference to the accompanying drawings, in which:

Fig. 1 schematically illustrates a SEM utilizing a high brightness electron
10 emission device according to the invention;

Fig. 2 illustrates more specifically the electron emission device suitable to be used in the SEM of Fig. 1;

Fig. 3A-3C graphically illustrate the results of the simulation of operation of the device of Fig. 2 showing improved brightness thereof;

15 **Figs. 4A and 4B** schematically illustrate how the device of Fig. 2 is used with a micro-column;

Figs. 5A to 5C illustrate some more features of the present invention;

Figs. 6A to 6D illustrate electron source devices according to the invention designed so as to be used in a lithography tool; and

20 **Fig. 6E** illustrates the results of a computer simulation of the operation of the lithography tool of Figs. 6A-6D.

DETAILED DESCRIPTION OF A PREFERRED EMBODIMENT

Referring to Fig. 1, there is schematically illustrated a scanning electron microscope, generally designated **1**, constructed according to one embodiment of
25 the invention, for inspecting a sample **2** or for processing it with an electron beam. The microscope **1** comprises such main constructional parts as an electron source device **4** and an electron beam column **6** that directs a primary beam towards the sample **2** and directs secondary and back-scattered electrons towards a detector

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means **8**. The latter is appropriately accommodated in the path of electrons knocked out from the sample **2** as a result of its interaction with a primary electron beam.

As more specifically illustrated in Fig. 2, the electron source device **4** according to the present invention comprises a single nanotube or nanotube bundle **10B** located in a crater **11** formed in a conducting layer **10A**, and an anode-electrode **12**. A nanotube **10B** is formed on a metal catalyst **25** on the bottom of the crater **11**, such that a tip **15** of the nanotube is located inside the crater **11**. The layer **10A** and anode-electrode **12** are spaced from each other by an insulating layer **13** with the thickness d_4 ranging from $1\mu\text{m}$ to $10\mu\text{m}$, and are made of suitable electrically conducting materials, such as silicon. Generally, the thickness of the insulator layer **13** is limited by the electrical breakdown conditions.

The nanotubes based gun **4** is fully compatible with silicon processes (e.g. lithography, micromachining and anodic bonding). It is also compatible with any other micro-machined or micro-fabricated columns including ceramic-based columns.

To fabricate the device **4** with the silicon-based integrated technology, the insulating layer **13** is deposited onto the substrate silicon layer **10A**, and the extractor lens layer **12** is formed on top of the insulating layer **13**. Then, the layers **10A**, **12** and **13** are patterned so as to form the crater **11** in the substrate layer **10A** and to form an aperture **24** above the crater **11**. All the layers may and may not be patterned in a single masking procedure. In the example of Fig. 2, the width d_3 of the crater **11** is equal to the diameters of the opening made in the layers **12** and **13**. In Fig. 1, however, an alternative example is shown, wherein the width of the crater is smaller than the diameter of the opening made in the insulating layer **13**. The layer **12** may be a metal electrode for electron extraction. The nanotube **10B** is formed on the metal catalyst **25** deposited onto a surface region of the crater. The process of producing a localized nanotube is known (Ren et al, Science **282**,1105(1998)).

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The nanotube **10B** has the length d_1 , and the tip **15** of the nanotube is spaced a distance d_2 from a plane defined by the top of the crater **11** (i.e., from the insulating layer **13**). The diameter d_3 of the aperture **24** is preferably similar to the diameter of the crater **11**. The preferred relationship between these parameters and the thickness d_4 of the insulating layer **13** is as follows: $d_1 \approx d_2 \approx d_4 \approx 0.5d_3$.

The main conceptual difference between the above design and prior art designs (e.g., US 5,872,422), is that the crater is made in the conductive layer, and such a conductive crater creates a lens structure within the electron gun preventing the divergence of the beam.

Turning back to Fig. 1, the electron beam column **6** is composed of one or more electric and/or magnetic lenses, generally at **14**, an aperture **16**, a beam deflection system **18**, and an objective lens **20**. The construction and operation of the electron beam column are known *per se*, and therefore need not be specifically described, except to note the following advantageous features of the column **6**. Due to the very good emission properties of the nanotube-based electron beam source **4**, namely, low energy spread and high brightness as will be described further below, the number, size and complexity of the column components are significantly reduced. In particular, almost no apertures are required. Accordingly, a relatively small percentage of the beam needs to be blocked by an aperture **16**. That is, the difference between a probe current (i.e., that reaching the sample **2**) and emitted current (i.e., that produced by the electron beam source **4**) is significantly smaller than in commercial sources. This is schematically illustrated as the figure, showing in solid lines an electron beam envelope **EB₁** produced by the electron beam source **4** and in dashed lines an electron beam envelope **EB₂** that is typically produced by the conventional electron source device. The dashed beam envelope schematically illustrates the divergence of the beam as occurs in the prior art without the gun design of the present invention.

Figs. 3A-3C illustrate the simulation results. Fig. 3A shows a half cut section of the cylindrical beam **EB₁**, z-axis being the axis of the device, i.e., an axis parallel to the axis of symmetry of the crater **11** ($z=0$ corresponding to the central

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bottom region of the crater), and r -axis being directed along the radius of the crater. The emission properties of the nanotube tip are the same as in the prior art (Nature, Vol. 389, 9th Oct 1997, pp 554-555), but the nanotube (of length d_1) is embedded in the conducting crater, leaving the distance d_2 between the tip of the nanotube and the 'edge' of the crater 11. In the simulation, the voltage used to extract the current is 100V for a 1 μ m insulator gap (thickness d_4). As indicated above, this parameter is determined conservatively to withstand the electrical breakdown voltage specifications of the insulator layer. The total current of 500nA is embedded within a radius 100nm at a distance of 4 μ m from the gun. In the present example 10 $d_1=d_2=d_4=1\mu\text{m}$ and $d_3=2\mu\text{m}$. The nanotube length d_1 is a tradeoff between the higher voltage that is required when the nanotube is immersed deep in the crater 11 and the collimation of the beam that is lost as the tip of the nanotube is approaching the edge of the crater.

The above dimensions are given as an example only. Generally, the criteria 15 for the determination of these dimensions are as follows:

- the depth of the tip in the crater (d_2) affects the amount of the decrease in the field enhancement;
- the diameter of the crater (which is preferably similar to the diameter of the aperture d_3), from lens symmetry considerations, affects mainly the amount of field enhancement at the tip. 20
- the thickness of the insulator layer d_4 is limited by the electrical breakdown conditions.

Fig. 3B shows a ray-tracing simulation of electrons being emitted from a prior art nanotube device (electron beam EB_2), the nanotube tips being identified 25 by the same reference number 15 in Figs. 3A and 3B to facilitate understanding. This actually presents the divergence of the rays from a gun that does not have such a conducting crater. The total current is again 500nA. The current in a spot with a 100nm radius at a distance of 4 μ m from the gun is 75nA, i.e., 15% of the original current. The overall current is consistent with the experimental values presented by 30 Saito (Nature, Vol. 389, 9th Oct 1997, pp 554-5). The extraction voltage used in this

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figure is 10V. The field is determined so that the field at the tip in the two configurations shown in Figs. 3A and 3B is identical.

A comparison of the two configurations is shown in Fig. 3C. The figure plots the total electric field E along the axis of the device vs. the distance along this
5 axis from the nanotube tip **15** to the gate (i.e., extracting electrode **12**), normalized to the ‘no-crater’ tip electric field. The solid line represents a ‘no-crater’ device (prior art) whereas the dashed line represents the nanotube with a ‘crater’ device (present invention), with values factorized so that the tip fields are unity for both cases. In order to obtain the same current, this factorization is achievable by
10 varying the voltage. The values of the field are arbitrary and normalized. It is evident that the conducting crater based design accelerates the beam within the gun so that the angular dispersion is diminished. The ‘penalty’ is the reduction of localized field enhancement by the crater. Consequently, increased voltage has to be used. The reduced angular divergence due to the provision of the crater is evident.

15 The advantages of the conducting crater based technique may be easily understood from the following tentative argument: The electric field is considerably enhanced on the nano-scale distance, near the nanotube’s tip (i.e., local field enhancement). The nano-tip emits with considerable transverse dispersion, which is the main cause for the low brightness. The crater reduces the field amplification,
20 but, being conducting, it creates a parallel beam on a larger scale. A thin carbon nanotube or a thin bundle of a few nanotubes causes large field enhancement which is localized on the ‘nano’ scale. The crater decreases this field enhancement, so higher applied voltage is needed. Due to the superior field emission properties of nanotubes, this increased voltage is not prohibited by electrical-breakdown
25 conditions. The crater also acts as a lens for the immersed beam. The net result is a beam with decreased angular divergence. A further significant advantage of the crater is the protection of the nanotube or nanotubes from mechanical damage. The nanotubes that are situated in the crater are protected from mechanical damage.

It should be noted, although not specifically shown, that the nanotube-based
30 electron beam source device **4** comprises a gun chamber having a vacuum inlet.

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Due to the use of nanotubes based gun of the present invention, it may be sufficient to have high vacuum (10^{-6} - 10^{-8} Torr), rather than ultra high vacuum (10^{-8} - 10^{-9} Torr) in the gun chamber, in contrast to conventional field-emission SEM systems. The high vacuum ensures a sufficient electron mean-free path as well as stability of the electron gun. The crater also protects the nanotube from “poor” vacuum conditions. The crater-based design suppresses possible side emission along the length of the nanotube.

Additionally, one advantageous feature of the SEM 1 (Fig. 1), as compared to the conventional SEM (for example, that commercially available from FEI Inc.), is the reduced chromatic aberrations, due to the reduced energy spread of the electron beam produced by the nanotube-based electron source device 4. The small energy spread is due to the resonant-tunneling process (two-level emission system) of electron emission from nanotubes.

Another advantage is the reduced spherical aberrations that result from the reduced angular divergence of the beam at the gun exit.

It should be noted that, although the above description relates to a SEM, the electron beam source device 4 could be utilized in an EBL as well as in other tools that utilize an electron beam. The electron beam source device according to the invention can be utilized in small-scale devices, such as a miniaturized SEM (micro-column), which can be used in various fields.

The miniaturization of SEM and other E-beam tools has unique advantages. A miniature SEM can be brought to the sample instead of bringing the sample to a standard SEM. In other words, the miniature SEM can be used as an integrated tool, rather than being a stand-alone machine. As indicated above, electron microscopy systems are used extensively in the semiconductors industry. The present invention will allow a low voltage, high resolution SEM, that will do the desired tasks in-situ.

The quality of the nanotubes based electron source that is proposed in the present invention, and the compatibility with silicon technology, makes it an optimal electron source for miniaturization. Micro-columns are miniature SEMs,

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typically constructed from layers of silicon or silicon and Pyrex. A micro-column contains most of the components of an electron beam column (apertures, lenses, scanner and detector). The factor that so far impeded the development and commercialization of this device is the absence of a sufficiently bright electron
5 source that will have one or more of the following properties: compatibility with silicon technologies; and stability without resorting to heating.

Fig. 4A illustrates the integration of the nanotube-based source device according to the invention into a micro-column **50**. The typical column components that follow the electron beam source device **4** are a spacer **51**, that can be aligned
10 with an optical fiber **52** positioned in grooves **53**, an aperture **54**, a scanner **55**, an electrostatic (Einzel) lens **56** and a detector **57**. The beam **58** is led through these components to the sample **59**. The elevated optical quality of the source **4**, may lead to a reduction in the number of column components in the micro-column **50**.

It is important to note that the miniaturization of the electron source device
15 also allows the possibility of arrayed operation on a commensurate scale with present and future semiconductor chip-size. This concept is illustrated in Fig. 4B. It shows a multiple-column structure **60** formed by an array of parallel identical nanotube-based micro-columns, generally at **62**, which can be separately addressed electrically, as illustrated in the figure in a self-explanatory manner. Obviously, a
20 two-dimensional array (or matrix) of such micro-columns can be assembled together.

It should be understood that the use of such an array of N micro-columns in an EBL tool would significantly improve its throughput. The arrayed operation will have better performance than high-resolution optical steppers. The multiple-column
25 structure may also be used for multiple-beam inspection, metrology and direct writing techniques.

The cathode-electrode may carry an array of nanotubes, wherein either a row of spaced-apart nanotubes is located in a common elongated crater, or an array of craters is formed in the conducting substrate each carrying a corresponding one of
30 the nanotubes. Figs. 5A and 5B illustrate front and top views, respectively, of an

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electron source device **40** composed of a cathode-electrode **42** and an anode-electrode **43** spaced from each other by an insulating layer **44** (e.g., vacuum). The cathode-electrode **42** includes a substrate **42A** (e.g., silicon) carrying an array **42B** of nanotubes in crater(s) (which are not specifically shown). An extractor lens **43** is formed as a plurality of spaced-apart apertures **43A** in the anode-electrode. As is better seen in Fig. 5B, the extractor lens **43** is in the form of several concentric rings - three rings in the present example, the rings sections serving as apertures, generally at **43A**. The rings-based design of the mask may be replaced by any other concentric polygon-structure (e.g., rectangular). Fig. 5C illustrates a matrix **400**, composed of elements **43**, which is suitable for use in the electron gun **40**.

Referring to Figs. 6A to 6C, there is illustrated an electron source device **70** designed to be used as part of a lithography tool. In the electron source device **70** shown in Fig. 6A, effective (emitting) nanotube-containing regions **72** are shaped and distributed within a substrate layer (e.g., silicon), in accordance with a pattern to be produced on a sample (e.g., semiconductor wafer) by the lithography tool. In other words, each of the regions presents a specific feature of the pattern, and the spaces between these regions correspond to those between the pattern features. Each line of the region **72** is shaped in the form of a conducting elongated crater to create parallel beams. The lines can be fabricated using electron beam lithography techniques to create the pattern of catalyst nanoparticles on which the nanotubes are grown. According to an alternative embodiment of the invention, shown in Fig. 6B, a substrate layer (cathode electrode) **71** is uniformly covered with nanotubes in craters, and each nanotube or group of nanotubes is addressed electrically. As shown in Fig. 6C, a wafer **73** to be patterned may be placed in front of the nanotubes containing region or located on a stage or stepper (not shown), and the pattern is created by moving the wafer with respect to the layer **71**.

In a preferred embodiment of the invention, the nanotubes will grow in conducting “elongated craters” or grooves **74**, as shown in Fig. 6C. The grooves **74** may be created by standard etching techniques. They are used for collimating the electron beams, as exemplified in the crater-based design. The extractor electrode

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will be the wafer 73 itself that will be placed in “proximity focus” to the emitting surface. The average nanotubes diameter can be a few nanometers, and the average distance between nanotubes can be the same. According to the example of Fig. 6D, a modification to assist in extracting the electrons, instead of biasing the wafer, can
5 be an elongated gate illustrated by layers 75 and 76. But in principle the voltage can be applied to the wafer to be patterned.

As shown by the simulation results presented in Fig. 6E, the beam in a distance x of $5\mu\text{m}$ from the crater is smaller than 100nm in diameter. The parameters x and y are used to highlight the fact that figure shows a two
10 dimensional cross-section of an elongated crater. The current available in a 100nm spot from the crater design is up to 500nA , which is more than required for writing on a resist. This current density is available at a working distance of $5\mu\text{m}$ from the gun. Larger working distances are also possible.

Since the electron source device that is based on fiber(s), e.g., nanotube(s),
15 in a conducting crater emits with sufficient brightness to be used in electron microscopy, it is evident that a matrix of craters is suitable for a field emission display, where each beamlet correspond to a pixel. Thus, the current invention is also suitable for flat panel displays.

The advantages of the present invention are thus self-evident. The electron
20 source device according to the invention enables to solve various constructional and operational problems of electron source device based systems, such as electron microscopes, lithography tools and flat displays. Due to the small size of the nanotube-based electron source device and relaxed vacuum requirements, the entire system can have a desirably small footprint, and can allow for assembling a
25 multiple-column arrangement to be advantageously used in various applications. Due to the elevated optical performance of the electron gun and reduced chromatic and spherical aberrations of the associated electron beam, the performance of the system is significantly improved. In fact, the invention allows to the useful utilization of nanotubes in an electron gun. The use of “patterned”
30 cathode-electrode, and preferably by means of the same anode-electrode, the

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construction and operation of a lithography tool utilizing such an electron source device is significantly improved.

Those skilled in the art will readily appreciate that various modifications and changes can be applied to the preferred embodiments of the invention as
5 hereinbefore exemplified without departing from its scope defined in and by the appended claims.

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CLAIMS:

1. A device to be applied to a sample for processing it by at least one electron beam, the device comprising an electron source device that comprises an electrode in the form of a first conductive layer carrying at least one electrons emitting fiber
5 located inside a crater formed in said first conductive layer for collimating the electron beam produced by the fiber, and an extracting electrode insulated from the first layer, the extracting electrode being formed with at least one aperture located above the crater, the device thereby providing a desired angular divergence of the electron beam.
- 10 2. The device according to Claim 1, wherein said at least one electrons emitting fiber is nanotube.
3. The device according to Claim 1, wherein said at least one fiber is grown on a catalyst formed on the surface of the crater.
4. The device according to Claim 1, wherein the extracting electrode is in the
15 form of a second layer spaced from the first layer by an insulating material, formed in an aligned manner.
5. The device according to Claim 1, wherein said processing includes at least one of monitoring, inspection/review, patterning, mask-making or excitation technique.
- 20 6. The device according to Claim 1, wherein for given nanotube dimensions, a diameter of said at least one aperture, a distance between the fiber tip and a plane defined by a top edge of the crater, and a width of the crater are selected so as to provide maximal optical performance and high emitted current.
7. The device according to Claim 6, wherein for given fiber dimensions, the
25 following parameters are approximately identical: a diameter of said at least one aperture; a distance between the fiber tip and a plane defined by a top edge of the crater; and a width of the crater.
8. The device according to Claim 1, also comprising an electron beam column for directing said at least one electron beam towards the sample, wherein
30 the electron beam column a micro-column produced by an integrated technology.

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9. The device according to Claim 8, wherein said electron source device is integrated into the microcolumn by anodic bonding.

10. The device according to Claim 1, wherein the first layer electrode carries a plurality of fibers, and the extracting electrode is formed with a plurality of spaced-apart apertures.

11. The device according to Claim 3, wherein said extracting electrode formed with at least one aperture is used as a mask for depositing catalyst therethrough.

12. The device according to Claim 10, wherein said plurality of spaced-apart apertures creates a plurality of gates each associated with a fiber-containing region therebelow.

13. The device according to Claim 10, wherein said spaced-apart apertures are formed as sections of a plurality of spaced-apart concentric rings.

14. The device according to Claim 10, wherein said spaced-apart apertures are formed as sections of a plurality of spaced-apart concentric polygons.

15. 15. The device according to Claim 10, wherein said plurality of apertures may be in the form of a desired pattern to be produced on the surface of the sample, said device serving as a lithography tool.

16. The device according to Claim 10, wherein said plurality of apertures presents a mask through which the plurality of fibers are grown on the first layer.

20 17. The device according to Claim 10, wherein the second conductive layer is in form of a pattern having spaced-apart apertured conductive regions, each conductive region being separately operated by a power source, thereby serving as a separate gate for the corresponding at least one fiber located on the first layer below this conductive region.

25 18. The device according to Claim 19, functioning as a display, each apertured conductive region together with said corresponding at least one fiber presenting a pixel of the display.

19. The device according to Claim 1, and also comprising a plurality of the electron source devices each associated with a corresponding one of a plurality of

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electron beam columns, which assembled together for producing a corresponding plurality of electron beams.

20. The device according to Claim 20, wherein each of the electron beam columns is a micro-column.

5 **21.** An electron microscope to be applied to a sample, the microscope comprising an electron source device and an electron beam column, wherein the electron source device comprises an electrode in the form of a first conductive layer carrying at least one electrons emitting fiber located inside a crater formed in said first conductive layer for collimating the electron beam produced by the fiber, and
10 an extracting electrode insulated from the first layer, the extracting electrode being formed with at least one aperture located above the crater, the device thereby providing a desired angular divergence of the electron beam.

22. A lithography tool for processing a sample to form its surface with a predetermined pattern, the tool comprising an electron source device having a
15 plurality of electrons emitting fibers producing a plurality of beams each corresponding to one of the pattern features, the beams being spatially separated and aligned in a manner corresponding to the alignment of the pattern features to be obtained on the surface of the sample.

23. The lithography tool according to Claim 23, wherein the fibers are located
20 inside at least one crater formed in an electrically conductive substrate insulated from said sample.

24. The lithography tool according to Claim 23, wherein said sample serves as an extracting electrode and is placed in proximity focus to an emitting surface defined by the fibers' tips.

25 **25.** A lithography tool to be applied to a sample to produce a predetermined pattern on the surface of the sample, the lithography tool comprising an electron source device and an electron beam column, wherein the electron source device comprises an electrode in the form of a first conductive layer carrying at least one electrons emitting fiber located inside a crater formed in said first conductive layer
30 for collimating the electron beam produced by the fiber, and an extracting electrode

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insulated from the first layer, the extracting electrode being formed with at least one aperture located above the crater, the device thereby providing a desired angular divergence of the electron beam.

26. The lithography tool according to Claim 26, wherein said first layer carries
5 a plurality of fibers located in the craters arranged in accordance with a predetermined pattern to be produced on the surface of the sample.

27. The lithography tool according to Claim 27, wherein said extracting electrode is formed with a plurality of spaced-apart apertures each aperture located above a corresponding one of the craters.

10 28. The lithography tool according to Claim 26, wherein said first layer is uniformly covered with a plurality of spaced-apart fibers, each fiber being addressed electrically; and the sample to be patterned is supported below the first layer for movement relative to the first layer.

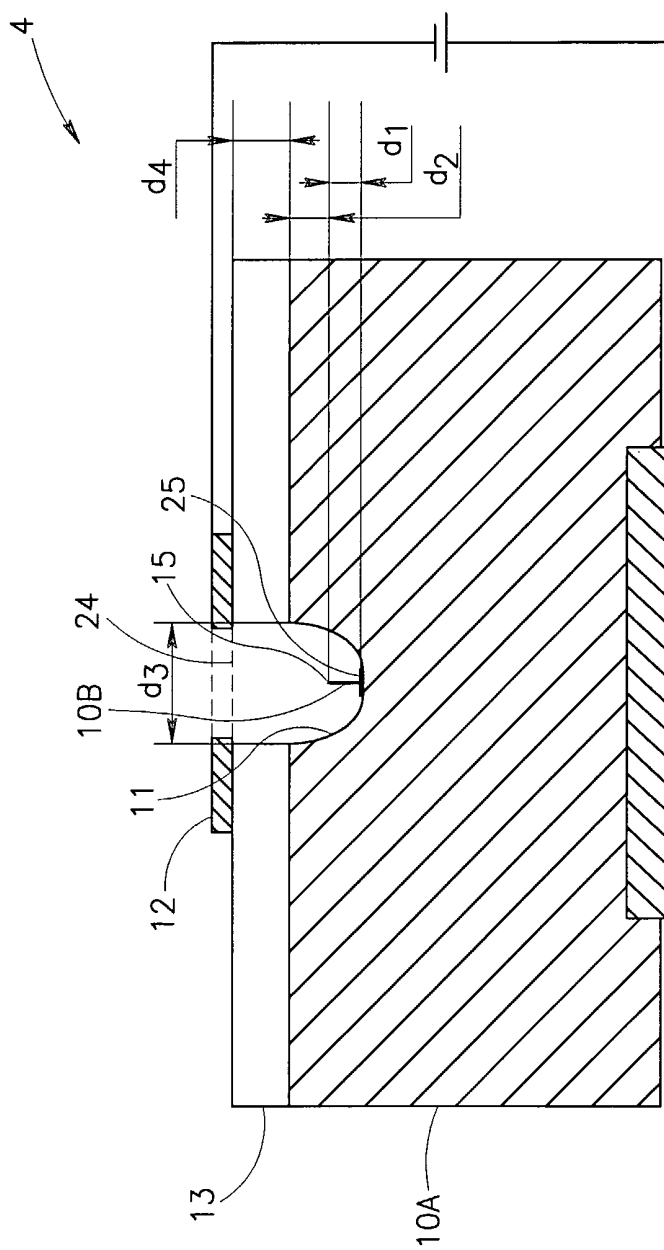


FIG. 2

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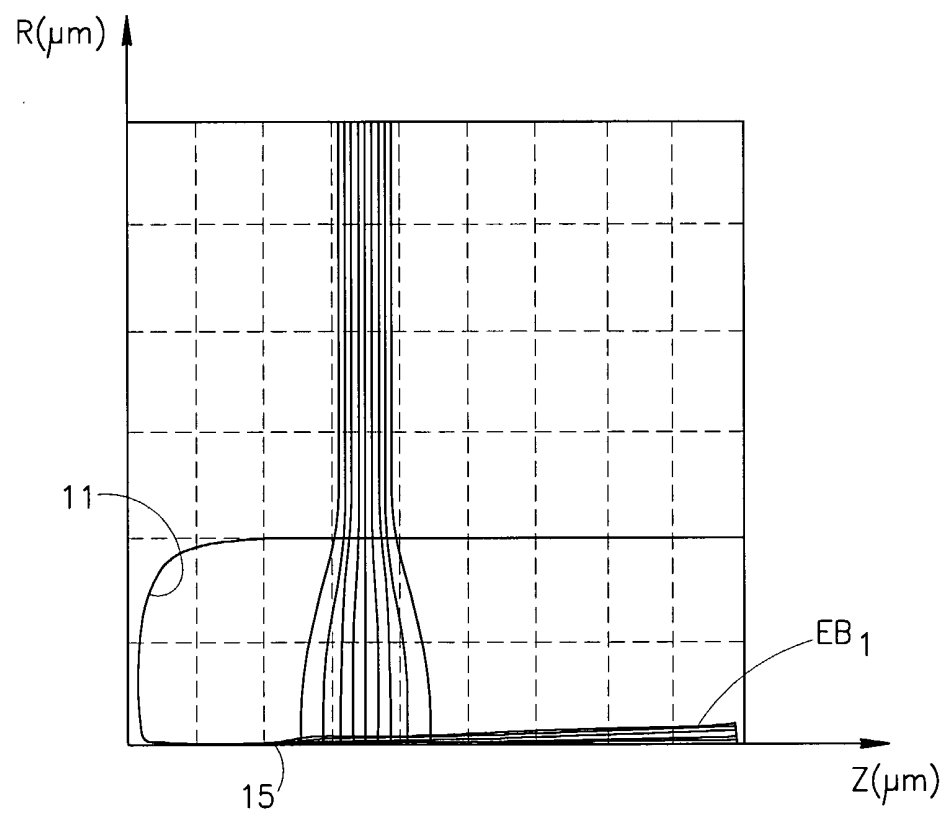


FIG.3A

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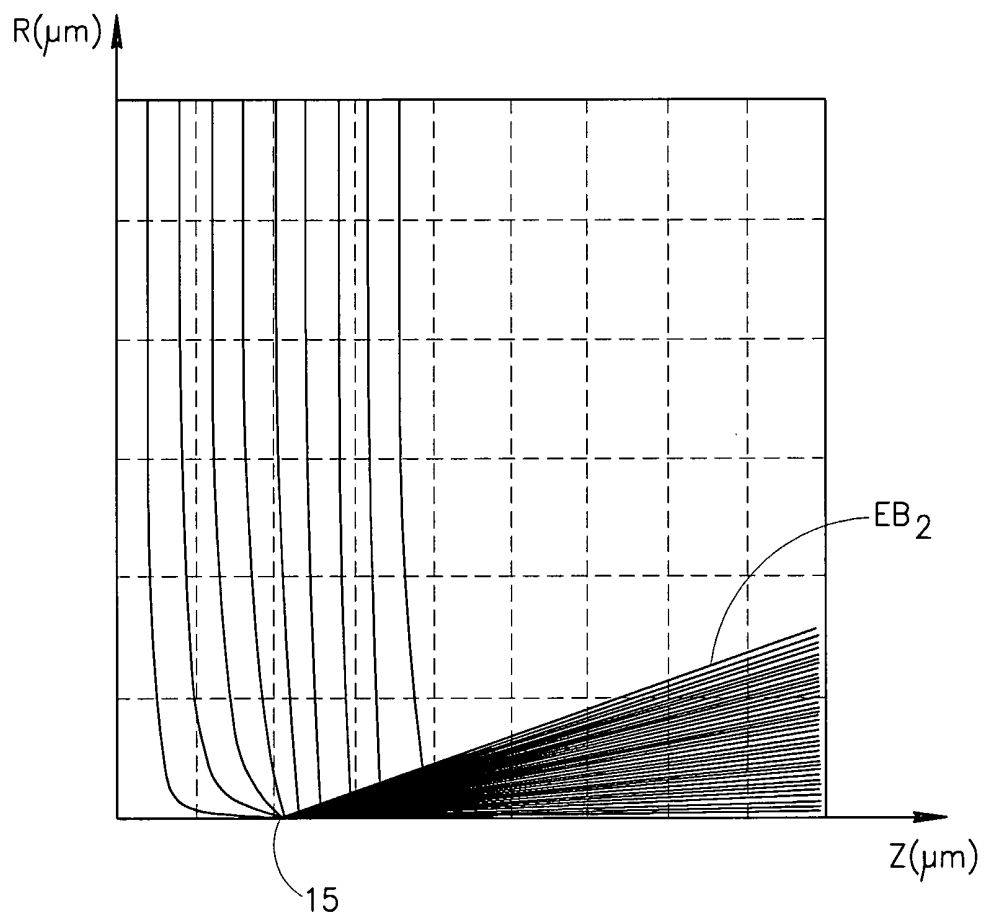


FIG.3B

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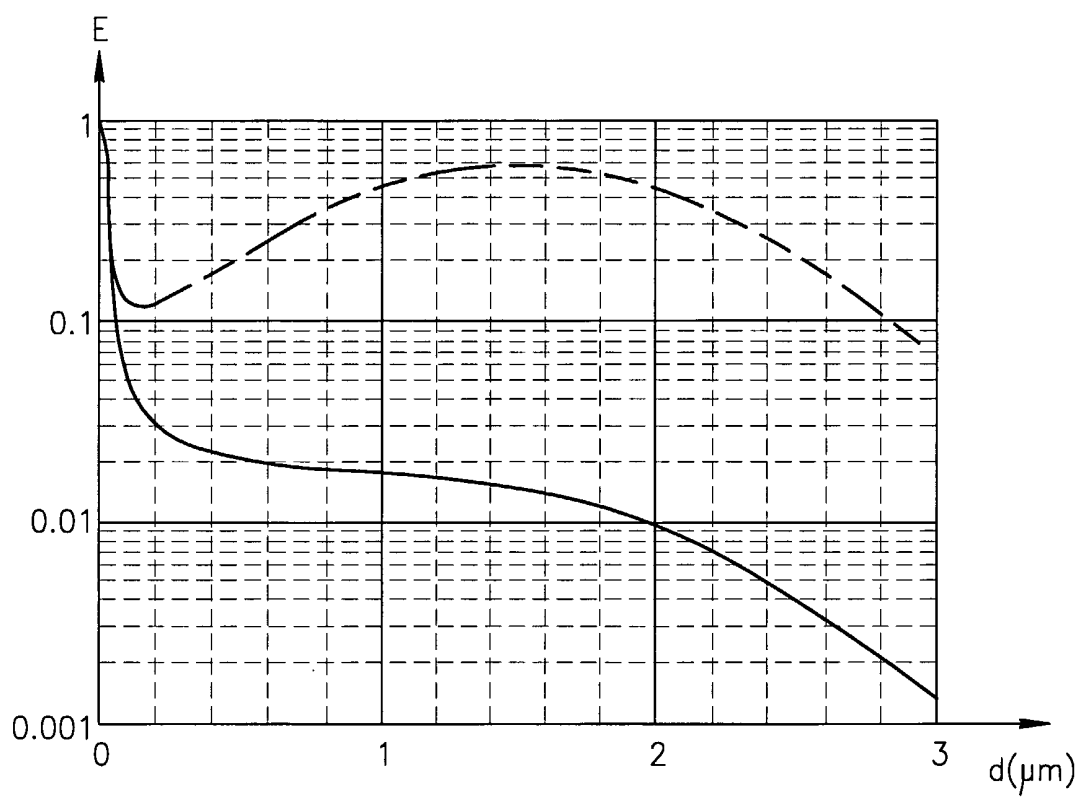


FIG.3C

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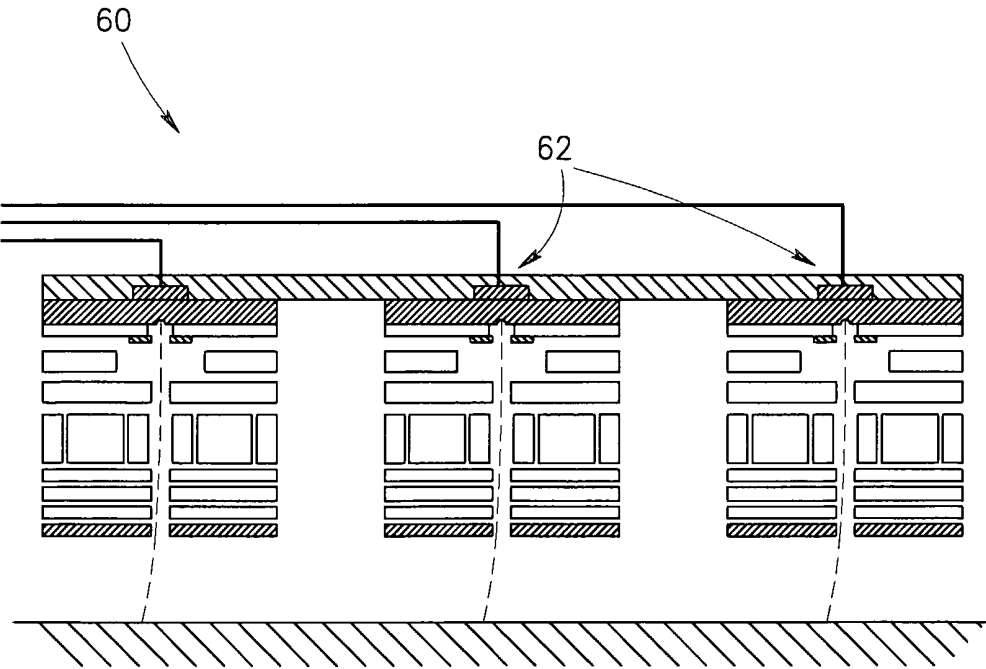
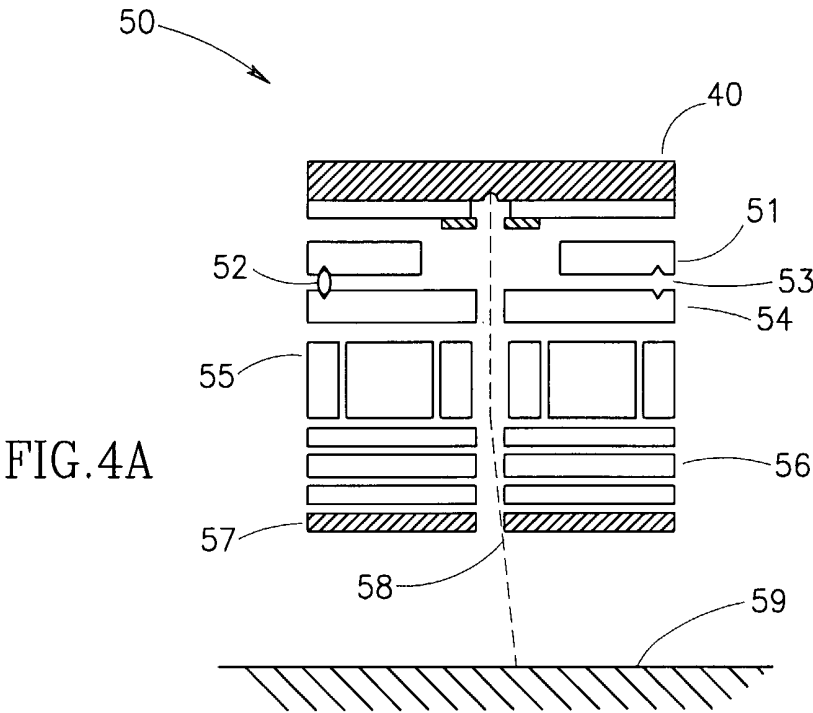


FIG.4B

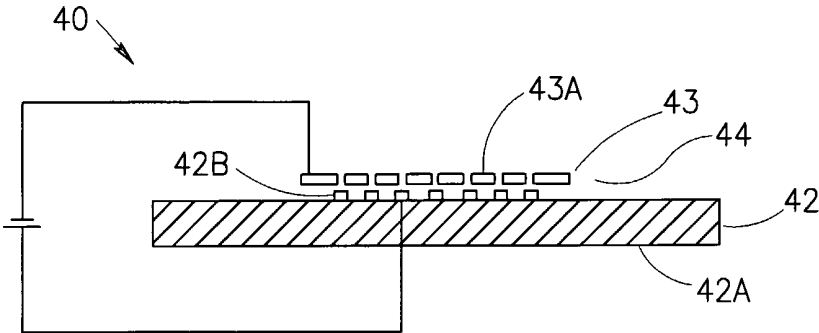


FIG. 5A

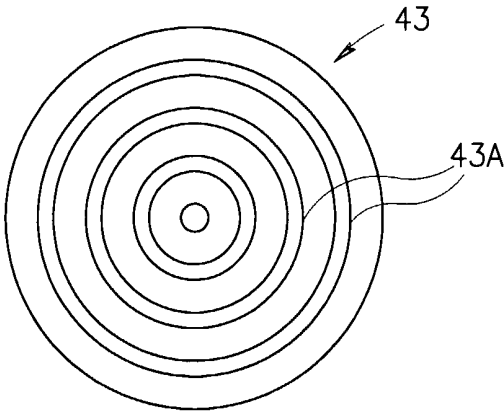


FIG. 5B

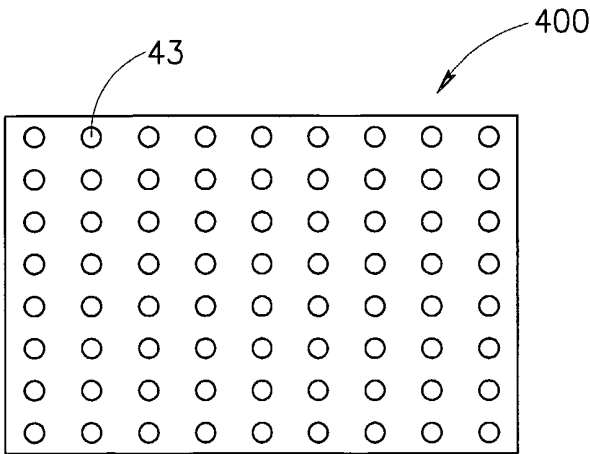


FIG. 5C

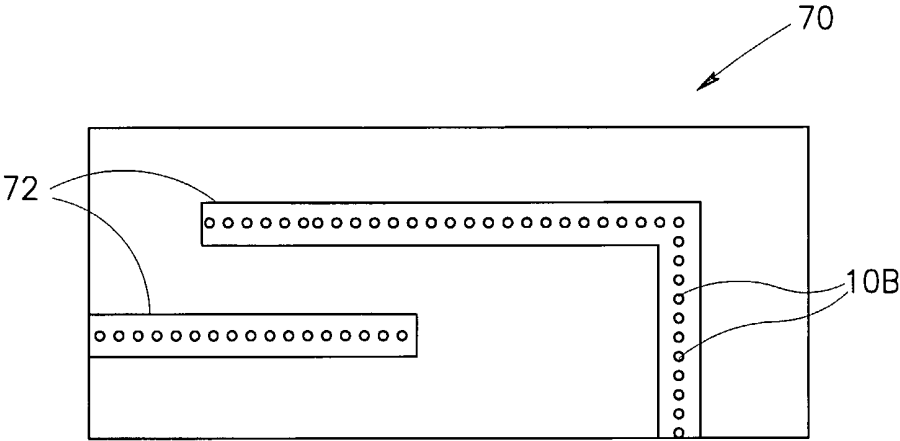


FIG. 6A

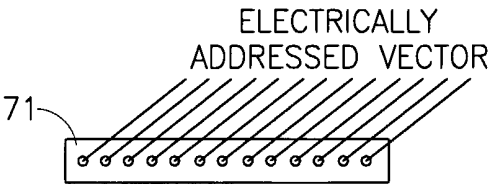


FIG. 6B

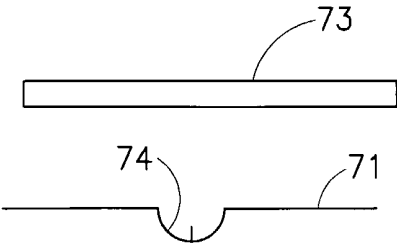


FIG. 6C

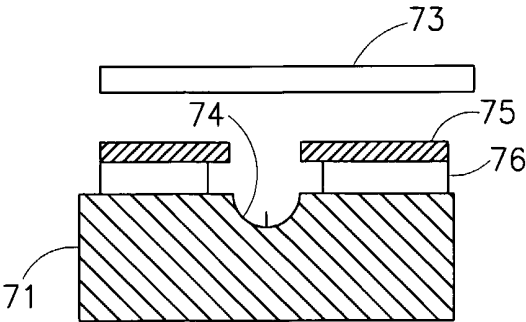


FIG. 6D

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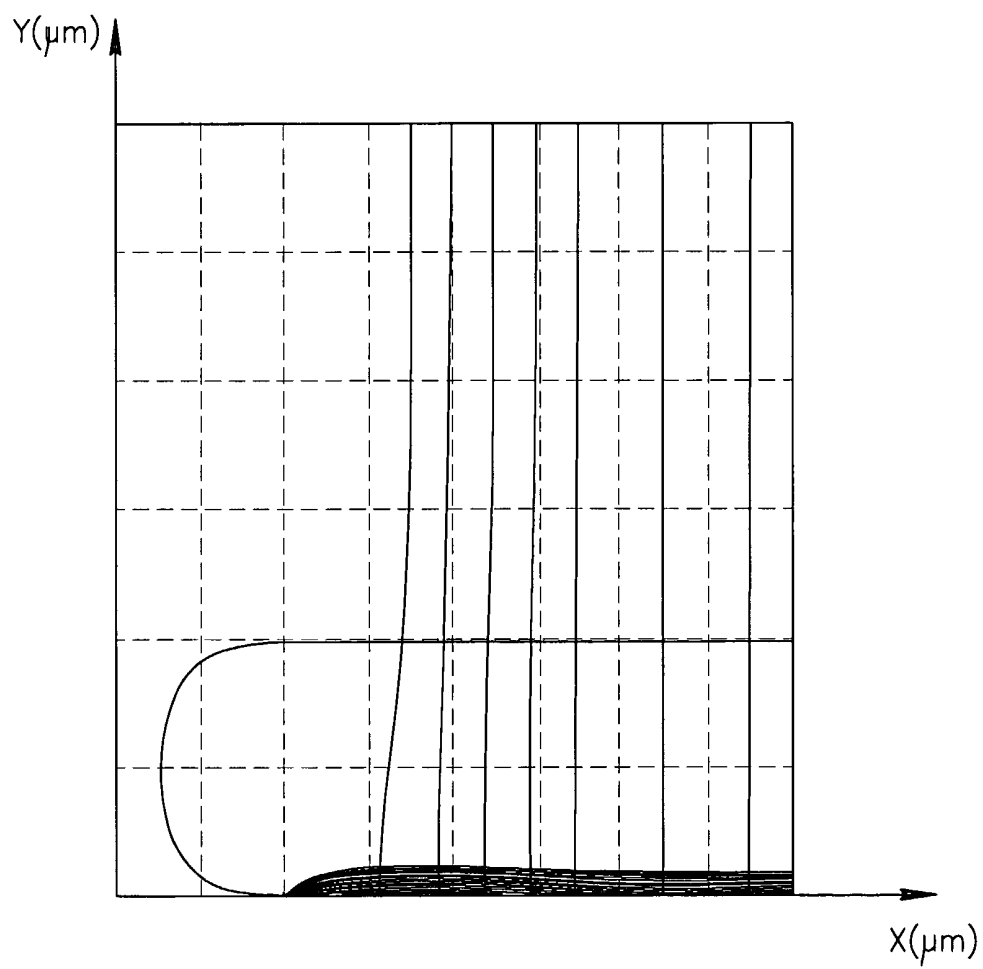


FIG.6E